

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a multi-color light emitting diode package. The multi-color light emitting diode package mounted thereon with at least three light emitting diodes comprises a substrate formed at the upper surface thereof with a pattern including three first terminals, and a single second terminal, first and second light emitting diodes, the diodes being mounted on a conductive mount pattern extending from the second terminal, and all formed at their upper surfaces with first and second electrodes, and a single zener diode chip having two zener diodes, the zener diode chip being mounted on the conductive mount pattern, and formed at a lower surface thereof with a single second electrode, and at an upper surface thereof with two first electrodes.